



**MICROCIRCUIT DATA SHEET**

**MN54ABT541-X REV 0A0**

Original Creation Date: 11/01/95  
 Last Update Date: 03/31/97  
 Last Major Revision Date: 03/19/97

**OCTAL BUFFER/LINE DRIVER WITH TRI-STATE OUTPUTS**

**General Description**

The ABT541 is an octal buffer and line driver with TRI-STATE outputs designed to be employed as a memory and address driver, clock driver or bus-oriented transmitter/receiver. The ABT541 is similar to the ABT244 with broadside pinout.

**Industry Part Number**

54ABT541

**NS Part Numbers**

54ABT541E-QML \*  
 54ABT541J-QML \*\*  
 54ABT541W-QML \*\*\*

**Prime Die**

NB541

**Controlling Document**

See Features Page

**Processing**

MIL-STD-883, Method 5004

**Quality Conformance Inspection**

MIL-STD-883, Method 5005

Subgrp	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

**Features**

- Non-inverting buffers
- Output sink capability of 48mA, source capability of 24 mA
- Guaranteed latching protection
- Flow-through pinout for ease of PC board layout
- Disable time less than enable time to avoid bus contention
- High impedance glitch free bus loading during entire power up and power down cycle.
- Non-Destructive hot insertion capability.
- SMD : 5962-9471801Q2A\*, QRA\*\*, QSA\*\*\*

**(Absolute Maximum Ratings)**

(Note 1)

Vcc Pin Potential to Ground Potential	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30mA to +5.0mA
Voltage Applied To Any Output In the Disabled or Power-Off State In The High State	-0.5V to 5.5V -0.5V to Vcc
Current Applied To Output In The Low State (Max)	96mA
Junction Temperature (Tj) Ceramic	+175C
Thermal Resistance Junction-To-Case (Theta JC)	See Mil-Std 1835
Storage Temperature	-65C to +150C
Lead Temperature (Soldering, 10 seconds)	+300C
ESD Classification	Class 2
Maximum Power Dissipation	500 mW

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

**Recommended Operating Conditions**

Supply Voltage (Vcc)	4.5V to 5.5V
Operating Temperature	-55C to +125C
Minimum Input Edge Rate (dV/dt)	
Data Input	50 mV/ns
Enable Input	20 mV/ns
Clock Input	100mV/ns
Maximum Output Current	
High Level (Ioh)	-24 mA
Low Level (Iol)	48 mA

## Electrical Characteristics

### DC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)  
DC: 4.5V to 5.5V Temp Range: -55C to 125C

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
ICCH	Supply Current	VCC=5.5V, VINH=5.5V, VINL=0.0V	1, 4	VCC		250.0	uA	1, 2, 3
ICCL	Supply Current	VCC=5.5V, VINH=5.5V, VINL=0.0V	1, 4	VCC		30.0	mA	1, 2, 3
ICCZ	Supply Current	VCC=5.5V, VINH=5.5V, VINL=0.0V	1, 4	VCC		250.0	uA	1, 2, 3
ICCT	Supply Current per Input	VCC=5.5V, OE=0.0V Input under test=3.4V Other inputs=5.5V or 0.0V	1, 4	VCC		2.5	mA	1, 2, 3
		VCC=5.5V, OE=3.4V Other inputs=5.5V or 0.0V	1, 4	VCC		2.5	mA	1, 2, 3
		VCC=5.5V, OE=5.5V Input under test = 3.4V Other inputs = 5.5V or 0.0V	1, 4	VCC		50.0	uA	1, 2, 3
IIH	High Level Input Current	VCC=5.5V, VINH=5.5V	1, 4	IN		2.0	uA	1, 2, 3
IIL	Low Level Input Current	VCC=5.5V, VINL=0.0V	1, 4	IN		-2.0	uA	1, 2, 3
IOZH	Maximum TRI-STATE Leakage Current HIGH	VCC=5.5V, VOUT=2.7V VINL=0.0V, VIH (OE)=2.0V	1, 4	OUT		10.0	uA	1, 2, 3
IOZL	Maximum TRI-STATE Leakage Current LOW	VCC=5.5V, VOUT=0.5V VINH=5.5V, VIH (OE)=2.0V	1, 4	OUT		-10.0	uA	1, 2, 3
ICEX	Output High Leakage Current	VCC=5.5V, VOUT=5.5V VINH=5.5V	1, 4	OUT		50.0	uA	1, 2, 3
IOS	Output Short Circuit Current	VCC=5.5V, VOUT=0.0V VINH=5.5V	1, 4, 10	OUT	-100	-275	mA	1, 2, 3
IOS1	Output Short Circuit Current	VCC=5.5V, VOUT=2.5V VINH=5.5V	1, 4, 10	OUT	-50	-180	mA	1, 2, 3
IBVI	Input High Current Breakdown Test	VCC=5.5V, VINH=7.0V	1, 4	IN		7.0	uA	1, 2, 3
IZZ	Bus Drainage Test	VCC=0.0V, VOUT=4.5V, VINL=0.0V	1, 4	IN/OUT	-100	100	uA	1, 2, 3
VOL	Low Level Output Voltage	VCC=4.5V, IOL=48.0mA, VINH=4.5V, VINL=0.0V, VIH=2.0V, VIL=0.8V	1, 4	OUT		0.55	V	1, 2, 3

## Electrical Characteristics

### DC PARAMETERS (Continued)

(The following conditions apply to all the following parameters, unless otherwise specified.)  
DC: 4.5V to 5.5V Temp Range: -55C to 125C

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
VOH	High Level Output Voltage	VCC=4.5V, IOH=-24.0mA, VINH=4.5V, VINL=0.0V, VIH=2.0V, VIL=0.8V	1, 4	OUT	2.0		V	1, 2, 3
		VCC=4.5V, IOH=-3mA, VINH=4.5V, VINL=0.0V, VIH=2.0V, VIL=0.8V	1, 4	OUT	2.5		V	1, 2, 3
		VCC=5.0V, IOH=-3mA, VINH=5.0V, VINL=0.0V, VIH=2.0V, VIL=0.8V	1, 4	OUT	3.0		V	1, 2, 3
VID	Input Leakage Test	VCC=0.0V, IID=1.9uA, VINL=0.0V	1, 4	IN	4.75		V	1, 2, 3
VCD	Input Clamp Diode Voltage	VCC=4.5V, IKL=-18mA, VINH=4.5V, VINL=0.0V	1, 4	IN		-1.2	V	1, 2, 3
VOLP	Low Level Ground Bounce	VCC=5.0V, LOAD : 50pF / 500 OHMS	7, 8	OUT		1.1	V	4
VOLV	Low Level Ground Bounce	VCC=5.0V, LOAD : 50pF / 500 OHMS	7, 8	OUT		-1.45	V	4
VOHP	High Level VCC Bounce	VCC=5.0V, LOAD : 50pF / 500 OHMS	7, 8	OUT		1.5	V	4
VOHV	High Level VCC Bounce	VCC=5.0V, LOAD : 50pF / 500 OHMS	7, 8	OUT		-0.5	V	4
CIN	Input Capacitance	VCC=0.0V	7	IN		15.5	pF	4
COUT	Output Capacitance	VCC=5.0V	7	OUT		16.5	pF	4

## Electrical Characteristics

### AC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)  
AC: CL=50pF RL=500 OHMS TRISE/TFALL = 3.0ns

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
tpLH	Propagation Delay	VCC= 4.5V - 5.5V	2, 5	CP to On	1.0	4.1	ns	9
			2, 5	CP to On	1.0	5.0	ns	10, 11
tpHL	Propagation Delay	VCC= 4.5V - 5.5V	2, 5	CP to On	1.0	4.5	ns	9
			2, 5	CP to On	1.0	5.3	ns	10, 11
tpZL	Output Enable Time	VCC=4.5V - 5.5V	2, 5	$\overline{OE}$ to On	1.7	6.5	ns	9
			2, 5	$\overline{OE}$ to On	1.7	7.9	ns	10, 11
tpZH	Output Enable Time	VCC=4.5V - 5.5V	2, 5	$\overline{OE}$ to On	1.1	5.9	ns	9
			2, 5	$\overline{OE}$ to On	1.1	7.2	ns	10, 11
tpHZ	Output Disable Time	VCC=4.5V - 5.5V	2, 5	$\overline{OE}$ to On	1.5	6.6	ns	9
			2, 5	$\overline{OE}$ to On	1.5	7.5	ns	10, 11
tpLZ	Output Disable Time	VCC=4.5V - 5.5V	2, 5	$\overline{OE}$ to On	1.5	6.5	ns	9
			2, 5	$\overline{OE}$ to On	1.5	7.9	ns	10, 11

Note 1: SCREEN TESTED 100% ON EACH DEVICE AT -55C, +25C & +125C TEMP., SUBGROUPS 1,2,3,7 & 8.

Note 2: SCREEN TESTED 100% ON EACH DEVICE AT -55C, +25C & +125C TEMP., SUBGROUPS A9, A10 & A11.

Note 3: SCREEN TESTED 100% ON EACH DEVICE AT +25C TEMP. ONLY, SUBGROUP 9.

Note 4: SAMPLE TESTED (METHOD 5005, TABLE 1) ON EACH MFG. LOT AT +25C, +125C & -55C TEMP., SUBGROUPS A1, 2, 3, 7 & 8.

Note 5: SAMPLE TESTED (METHOD 5005, TABLE 1) ON EACH MFG. LOT AT +25C, +125C & -55C TEMP., SUBGROUPS A9, 10, 11.

Note 6: SAMPLE TESTED (METHOD 5005, TABLE 1) ON EACH MFG. LOT AT +25C TEMP. ONLY, SUBGROUP A9.

Note 7: NOT TESTED (GUARANTEED BY DESIGN CHARACTERIZATION DATA).

Note 8: MAX NUMBER OF OUTPUTS DEFINED AS (N). N-1 DATA INPUTS ARE DRIVEN 0V TO 3.0V. ONE OUTPUT AT @ VOL OR @ VOH.

Note 9: MAX NUMBER OF DATA INPUTS (N) SWITCHING. (N-1) INPUTS SWITCHING 0V TO 3.0V. INPUT-UNDERTEST SWITCHING: 3V TO THRESHOLD (VILD), 0V TO THRESHOLD (VIHD), FREQ.= 1 MHZ.

Note 10: MAXIMUM TEST DURATION NOT TO EXCEED ONE SECOND, NOT MORE THAN ONE OUTPUT SHORTED AT ONE TIME.

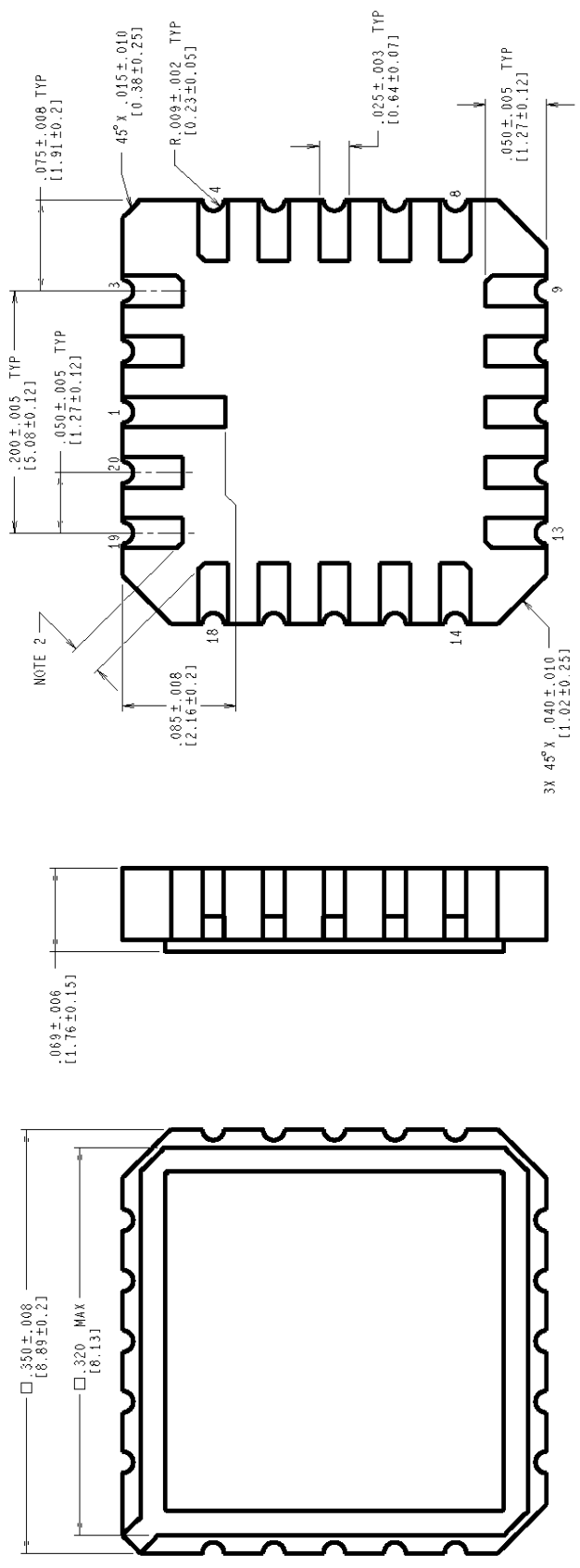
## Graphics and Diagrams

GRAPHICS#	DESCRIPTION
E20ARE	LDLESS CHIP CARRIER, TYPE C 20 TERMINAL (P/P DWG)
J20ARM	CERDIP (J), 20 LEAD (P/P DWG)
W20ARF	CERPAC (W), 20 LEAD (P/P DWG)

See attached graphics following this page.

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LI  
LE  
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REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
E	REVISE AND REDRAW.	10005	02/10/94
			DEG/



CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
  - 50 MICRONS/1.27 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICRONS/1.27-8.89 MICROMETERS NICKEL.
  - SOLDER DIP.
  - SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.
- CORNER PADS MAY HAVE A  $45^\circ$  X  $0.020$  IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE  $0.015$  IN/0.38mm DIMENSION.
- REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB, DATED 7/90.

<b>MIL/AERO CONFIGURATION CONTROL</b>	
<b>NATIONAL SEMICONDUCTOR CORPORATION</b>	
2000 Semiconductor Drive, Santa Clara, CA 95052-8000	
<b>APPROVALS</b>	<b>DATE</b>
DESIGN: <i>Deegee Brady</i>	02/10/94
DATE: CHG.	
ENGR: CHG.	
APPROVAL	
SCALE: N/A C	
SHEET: DRAWING NUMBER: 20	
TERMINAL: TYPE C, 20	
PROTECTION: N/A	
DRAWING NUMBER: MKT-E20A	
SHEET: 1 of 1	